

ABSTRACT

The present invention provides a heat sink unit that has a small mounting area and high radiating efficiency without breaking or damaging the IC package. The heat sink unit 1 includes a base 22, a heat sink 2, a unit base 4, a heat sink mount 5, a frame member 6, a first lever 8, and a second lever 7. When the frame member 6 reaches a confronting position, further rocking is restricted, the heat sink mount 5 supported by the frame member 6 moves downward, and the end surface of the heat sink 2 supported by the heat sink mount 5 comes into contact with the IC package.

<Figure 1>